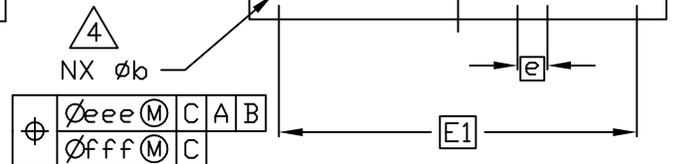
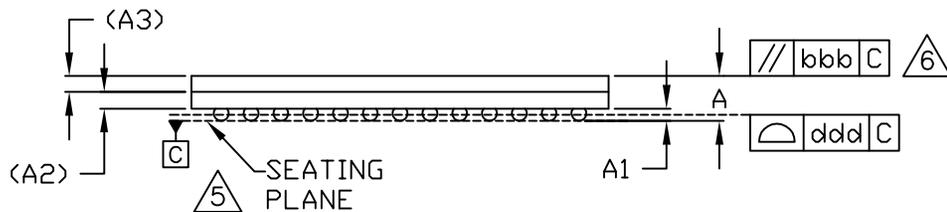


TOP VIEW



BOTTOM VIEW



SIDE VIEW

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994.
3. MATERIAL MUST COMPLY WITH BANNED AND RESTRICTED SUBSTANCES SPEC #10-0131.
4. DIMENSION  $b$  IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO DATUM PLANE  $C$
5. DATUM  $C$  (SEATING PLANE) IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
7. ALL DIMENSIONS APPLY TO BOTH LEADED (-) & PbfREE (+) PKG. CODES ONLY.
8. PACKAGE CODE: X16944-1

SYMBOL	DIMENSIONS		
	MIN.	NOM.	MAX.
A	1.410	1.500	1.590
A1	0.360	---	0.460
A2	0.560 REF.		
A3	0.530 REF.		
b	0.440	---	0.640
D	14.000 BSC		
D1	12.000 BSC		
E	14.000 BSC		
E1	12.000 BSC		
e	1.000 BSC		
aaa	0.200		
bbb	0.250		
ddd	0.100		
eee	0.250		
fff	0.100		
BALL DIAMETER	0.500		
N	169		

-DRAWING NOT TO SCALE-



TITLE: PACKAGE OUTLINE, 169 BALLS CSBGA, 14X14X1.5MM, 1.0MM PITCH, 6 LAYERS			
APPROVAL EDEN CHEN 1/6/12	DOCUMENT CONTROL NO. 21-0648	REV. A	1/1